

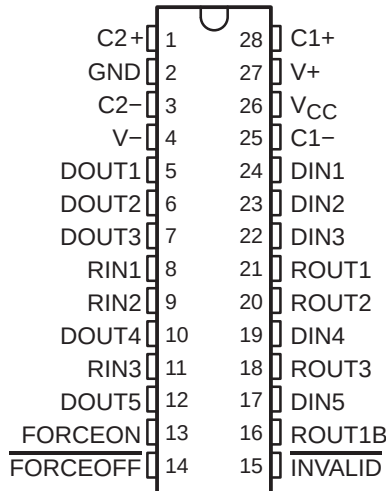
MAX3238

3-V TO 5.5-V MULTICHANNEL RS-232 LINE DRIVER/RECEIVER WITH ± 15 -kV ESD (HBM) PROTECTION

SLLS349J – JUNE 1999 – REVISED MARCH 2004

- RS-232 Bus-Pin ESD Protection Exceeds ± 15 kV Using Human-Body Model (HBM)
- Meets or Exceeds the Requirements of TIA/EIA-232-F and ITU v.28 Standards
- Operates With 3-V to 5.5-V V_{CC} Supply
- Operates Up To 250 kbit/s
- Five Drivers and Three Receivers
- Low Standby Current . . . 1 μ A Typical
- External Capacitors . . . $4 \times 0.1 \mu$ F
- Accepts 5-V Logic Input With 3.3-V Supply
- Always-Active Noninverting Receiver Output (ROUT1B)
- Alternative High-Speed Pin-Compatible Device (1 Mbit/s)
 - SNx5C3238
- Applications
 - Battery-Powered Systems, PDAs, Notebooks, Subnotebooks, Laptops, Palmtop PCs, Hand-Held Equipment, Modems, and Printers

DB OR PW PACKAGE
(TOP VIEW)



description/ordering information

The MAX3238 consists of five line drivers, three line receivers, and a dual charge-pump circuit with ± 15 -kV ESD (HBM) protection pin to pin (serial-port connection pins, including GND). The device meets the requirements of TIA/EIA-232-F and provides the electrical interface between notebook and subnotebook computer applications. The charge pump and four small external capacitors allow operation from a single 3-V to 5.5-V supply. In addition, the device includes an always-active noninverting output (ROUT1B), which allows applications using the ring indicator to transmit data while the device is powered down. These devices operate at data signaling rates up to 250 kbit/s and a maximum of 30-V/ μ s driver output slew rate.

ORDERING INFORMATION

T_A	PACKAGE [†]		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–0°C to 70°C	SSOP (DB)	Tube of 50	MAX3238CDB	MAX3238C
		Reel of 2000	MAX3238CDBR	
	TSSOP (PW)	Tube of 50	MAX3238CPW	MA3238C
		Reel of 2000	MAX3238CPWR	
–40°C to 85°C	SSOP (DB)	Tube of 50	MAX3238IDB	MAX3238I
		Reel of 2000	MAX3238IDBR	
	TSSOP (PW)	Tube of 50	MAX3238IPW	MB3238I
		Reel of 2000	MAX3238IPWR	

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

**TEXAS
INSTRUMENTS**

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description/ordering information (continued)

Flexible control options for power management are featured when the serial port and driver inputs are inactive. The auto-powerdown plus feature functions when FORCEON is low and $\overline{\text{FORCEOFF}}$ is high. During this mode of operation, if the device does not sense valid signal transitions on all receiver and driver inputs for approximately 30 s, the built-in charge pump and drivers are powered down, reducing the supply current to 1 μA . By disconnecting the serial port or placing the peripheral drivers off, auto-powerdown plus occurs if there is no activity in the logic levels for the driver inputs. Auto-powerdown plus can be disabled when FORCEON and $\overline{\text{FORCEOFF}}$ are high. With auto-powerdown plus enabled, the device activates automatically when a valid signal is applied to any receiver or driver input. INVALID is high (valid data) if any receiver input voltage is greater than 2.7 V or less than -2.7 V, or has been between -0.3 V and 0.3 V for less than 30 μs . INVALID is low (invalid data) if all receiver input voltages are between -0.3 V and 0.3 V for more than 30 μs . Refer to Figure 5 for receiver input levels.

Function Tables**EACH DRIVER**

INPUTS				OUTPUT DOUT	DRIVER STATUS
DIN	FORCEON	$\overline{\text{FORCEOFF}}$	TIME ELAPSED SINCE LAST RIN OR DIN TRANSITION		
X	X	L	X	Z	Powered off
L	H	H	X	H	Normal operation with auto-powerdown plus disabled
H	H	H	X	L	
L	L	H	<30 s	H	Normal operation with auto-powerdown plus enabled
H	L	H	<30 s	L	
L	L	H	>30 s	Z	Powered off by auto-powerdown plus feature
H	L	H	>30 s	Z	

H = high level, L = low level, X = irrelevant, Z = high impedance

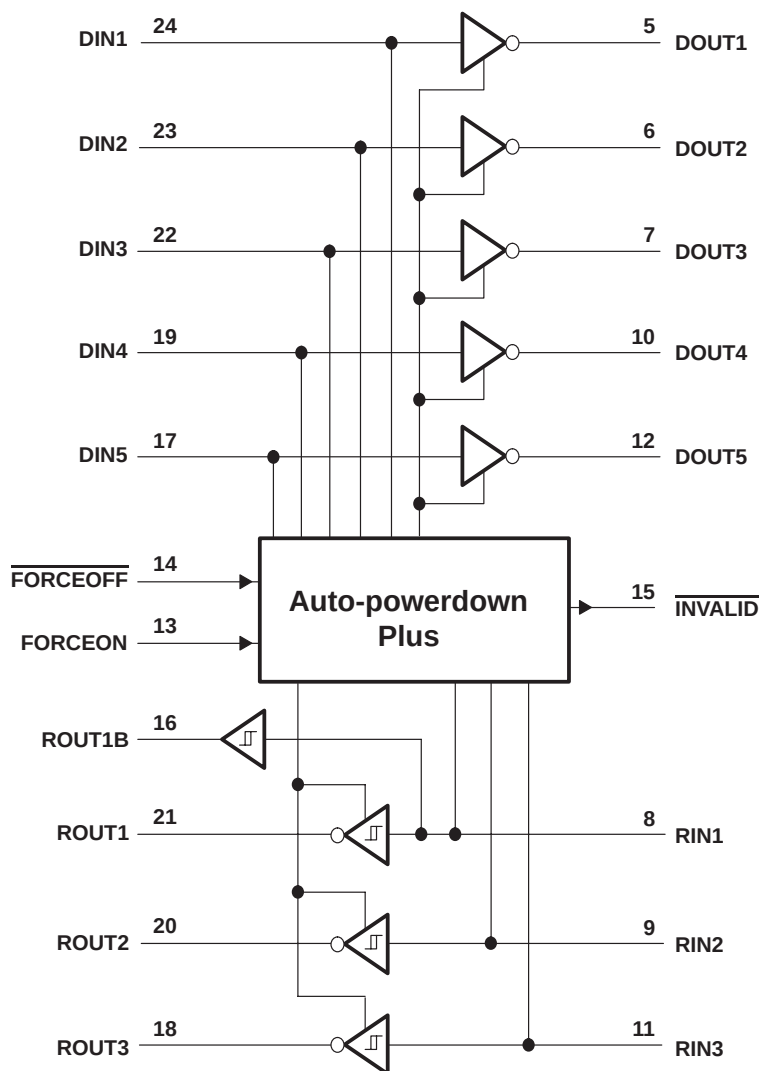
EACH RECEIVER

INPUTS				OUTPUTS		RECEIVER STATUS
RIN1	RIN2-RIN3	$\overline{\text{FORCEOFF}}$	TIME ELAPSED SINCE LAST RIN OR DIN TRANSITION	ROUT1B	ROUT	
L	X	L	X	L	Z	Powered off while ROUT1B is active
H	X	L	X	H	Z	
L	L	H	<30 s	L	H	Normal operation with auto-powerdown plus disabled/enabled
L	H	H	<30 s	L	L	
H	L	H	<30 s	H	H	
H	H	H	<30 s	H	L	
Open	Open	H	>30 s	L	H	

H = high level, L = low level, X = irrelevant, Z = high impedance (off), Open = input disconnected or connected driver off

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logic diagram (positive logic)



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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC} (see Note 1)	–0.3 V to 6 V
Positive output supply voltage range, V_+ (see Note 1)	–0.3 V to 7 V
Negative output supply voltage range, V_- (see Note 1)	0.3 V to –7 V
Supply voltage difference, $V_+ - V_-$ (see Note 1)	13 V
Input voltage range, V_I : Driver ($\overline{\text{FORCEOFF}}$, FORCEON)	–0.3 V to 6 V
Receiver	–25 V to 25 V
Output voltage range, V_O : Driver	–13.2 V to 13.2 V
Receiver (INVALID)	–0.3 V to $V_{CC} + 0.3$ V
Package thermal impedance, θ_{JA} (see Notes 2 and 3): DB package	62°C/W
PW package	62°C/W
Operating virtual junction temperature, T_J	150°C
Storage temperature range, T_{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltages are with respect to network GND.

2. Maximum power dissipation is a function of $T_J(\text{max})$, θ_{JA} , and T_A . The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_J(\text{max}) - T_A)/\theta_{JA}$. Operating at the absolute maximum T_J of 150°C can affect reliability.

3. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 4 and Figure 6)

			MIN	NOM	MAX	UNIT
Supply voltage		$V_{CC} = 3.3$ V	3	3.3	3.6	V
		$V_{CC} = 5$ V	4.5	5	5.5	
V_{IH}	Driver and control high-level input voltage	DIN, $\overline{\text{FORCEOFF}}$, FORCEON	$V_{CC} = 3.3$ V		2	V
			$V_{CC} = 5$ V		2.4	
V_{IL}	Driver and control low-level input voltage	DIN, $\overline{\text{FORCEOFF}}$, FORCEON			0.8	V
V_I	Driver and control input voltage	DIN, $\overline{\text{FORCEOFF}}$, FORCEON	0		5.5	V
V_I	Receiver input voltage		–25		25	V
T_A	Operating free-air temperature	MAX3238C	0		70	°C
		MAX3238I	–40		85	

NOTE 4: Testing supply conditions are C1–C4 = 0.1 μ F at $V_{CC} = 3.3$ V ± 0.15 V; C1–C4 = 0.22 μ F at $V_{CC} = 3.3$ V ± 0.3 V; and C1 = 0.047 μ F and C2–C4 = 0.33 μ F at $V_{CC} = 5$ V ± 0.5 V.

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 4 and Figure 6)

PARAMETER		TEST CONDITIONS	MIN	TYP‡	MAX	UNIT	
I _I	Input leakage current	$\overline{\text{FORCEOFF}}$, FORCEON	±0.01		±1	μA	
I _{CC}	Supply current (T _A = 25°C)	Auto-powerdown plus disabled	No load, $\overline{\text{FORCEOFF}}$ and FORCEON at V _{CC}		0.5	2	mA
		Powered off	No load, $\overline{\text{FORCEOFF}}$ at GND		1	10	
		Auto-powerdown plus enabled	No load, $\overline{\text{FORCEOFF}}$ at V _{CC} , FORCEON at GND, All RIN are open or grounded		1	10	μA

[‡] All typical values are at $V_{CC} = 3.3$ V or $V_{CC} = 5$ V, and $T_A = 25^\circ\text{C}$.

NOTE 4: Testing supply conditions are C1–C4 = 0.1 μ F at $V_{CC} = 3.3$ V ± 0.15 V; C1–C4 = 0.22 μ F at $V_{CC} = 3.3$ V ± 0.3 V; and C1 = 0.047 μ F and C2–C4 = 0.33 μ F at $V_{CC} = 5$ V ± 0.5 V.



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DRIVER SECTION

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 4 and Figure 6)

PARAMETER	TEST CONDITIONS	MIN	TYP [†]	MAX	UNIT
V _{OH} High-level output voltage	All DOUT at R _L = 3 k Ω to GND	5	5.4		V
V _{OL} Low-level output voltage	All DOUT at R _L = 3 k Ω to GND	-5	-5.4		V
I _{IH} High-level input current	V _I = V _{CC}		± 0.01	± 1	μ A
I _{IL} Low-level input current	V _I at GND		± 0.01	± 1	μ A
I _{OS} Short-circuit output current [‡]	V _{CC} = 3.6 V, V _O = 0 V		± 35	± 60	mA
	V _{CC} = 5.5 V, V _O = 0 V		± 40	± 100	
r _o Output resistance	V _{CC} , V ₊ , and V ₋ = 0 V, V _O = ± 2 V	300	10M		Ω
I _{off} Output leakage current	FORCEOFF = GND, V _O = ± 12 V, V _{CC} = 3 V to 3.6 V			± 25	μ A
	V _O = ± 10 V, V _{CC} = 4.5 V to 5.5 V			± 25	

[†] All typical values are at V_{CC} = 3.3 V or V_{CC} = 5 V, and T_A = 25°C.

[‡] Short-circuit durations should be controlled to prevent exceeding the device absolute power-dissipation ratings, and not more than one output should be shorted at a time.

NOTE 4: Testing supply conditions are C1–C4 = 0.1 μ F at V_{CC} = 3.3 V $\pm$ 0.15 V; C1–C4 = 0.22 μ F at V_{CC} = 3.3 V $\pm$ 0.3 V; and C1 = 0.047 μ F and C2–C4 = 0.33 μ F at V_{CC} = 5 V $\pm$ 0.5 V.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 4 and Figure 6)

PARAMETER	TEST CONDITIONS	MIN	TYP [†]	MAX	UNIT
Maximum data rate	C _L = 1000 pF, One DOUT switching, R _L = 3 k Ω , See Figure 1	150	250		kbit/s
t _{sk(p)} Pulse skew [§]	C _L = 150 pF to 2500 pF, R _L = 3 k Ω to 7 k Ω , See Figure 2		100		ns
SR(tr) Slew rate, transition region (see Figure 1)	V _{CC} = 3.3 V, R _L = 3 k Ω to 7 k Ω			30	V/ μ s
				4	

[†] All typical values are at V_{CC} = 3.3 V or V_{CC} = 5 V, and T_A = 25°C.

[§] Pulse skew is defined as |t_{PLH} – t_{PHL}| of each channel of the same device.

NOTE 4: Testing supply conditions are C1–C4 = 0.1 μ F at V_{CC} = 3.3 V $\pm$ 0.15 V; C1–C4 = 0.22 μ F at V_{CC} = 3.3 V $\pm$ 0.3 V; and C1 = 0.047 μ F and C2–C4 = 0.33 μ F at V_{CC} = 5 V $\pm$ 0.5 V.

RECEIVER SECTION

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 4 and Figure 6)

PARAMETER	TEST CONDITIONS	MIN	TYP [†]	MAX	UNIT
V _{OH} High-level output voltage	I _{OH} = -1 mA	V _{CC} - 0.6 V	V _{CC} - 0.1 V		V
V _{OL} Low-level output voltage	I _{OL} = 1.6 mA			0.4	V
V _{IT+} Positive-going input threshold voltage	V _{CC} = 3.3 V		1.5	2.4	V
	V _{CC} = 5 V		1.8	2.4	
V _{IT-} Negative-going input threshold voltage	V _{CC} = 3.3 V	0.6	1.2		V
	V _{CC} = 5 V	0.8	1.5		
V _{hys} Input hysteresis (V _{IT+} - V _{IT-})			0.3		V
I _{off} Output leakage current (except ROUT1B)	FORCEOFF = 0 V		±0.05	±10	μA
r _i Input resistance	V _I = ±3 V to ±25 V	3	5	7	kΩ

[†] All typical values are at V_{CC} = 3.3 V or V_{CC} = 5 V, and T_A = 25°C.

NOTE 4: Testing supply conditions are C1–C4 = 0.1 μF at V_{CC} = 3.3 V ± 0.15 V; C1–C4 = 0.22 μF at V_{CC} = 3.3 V ± 0.3 V; and C1 = 0.047 μF and C2–C4 = 0.33 μF at V_{CC} = 5 V ± 0.5 V.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 4)

PARAMETER	TEST CONDITIONS	MIN	TYP [†]	MAX	UNIT
t _{PLH} Propagation delay time, low- to high-level output	C _L = 150 pF, See Figure 3		150		ns
t _{PHL} Propagation delay time, high- to low-level output			150		ns
t _{en} Output enable time	C _L = 150 pF, R _L = 3 kΩ, See Figure 4		200		ns
t _{dis} Output disable time			200		ns
t _{sk(p)} Pulse skew [‡]	See Figure 3		50		ns

[†] All typical values are at V_{CC} = 3.3 V or V_{CC} = 5 V, and T_A = 25°C.

[‡] Pulse skew is defined as |t_{PLH} - t_{PHL}| of each channel of the same device.

NOTE 4: Testing supply conditions are C1–C4 = 0.1 μF at V_{CC} = 3.3 V ± 0.15 V; C1–C4 = 0.22 μF at V_{CC} = 3.3 V ± 0.3 V; and C1 = 0.047 μF and C2–C4 = 0.33 μF at V_{CC} = 5 V ± 0.5 V.

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AUTO-POWERDOWN PLUS SECTION

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 5)

PARAMETER	TEST CONDITIONS	MIN	TYP [†]	MAX	UNIT
V _{T+(valid)}	Receiver input threshold for INVALID high-level output voltage FORCEON = GND, FORCEOFF = V _{CC}			2.7	V
V _{T-(valid)}	Receiver input threshold for INVALID high-level output voltage FORCEON = GND, FORCEOFF = V _{CC}	-2.7			V
V _{T(invalid)}	Receiver input threshold for INVALID low-level output voltage FORCEON = GND, FORCEOFF = V _{CC}	-0.3		0.3	V
V _{OH}	INVALID high-level output voltage I _{OH} = -1 mA, FORCEON = GND, FORCEOFF = V _{CC}	V _{CC} -0.6			V
V _{OL}	INVALID low-level output voltage I _{OL} = 1.6 mA, FORCEON = GND, FORCEOFF = V _{CC}			0.4	V

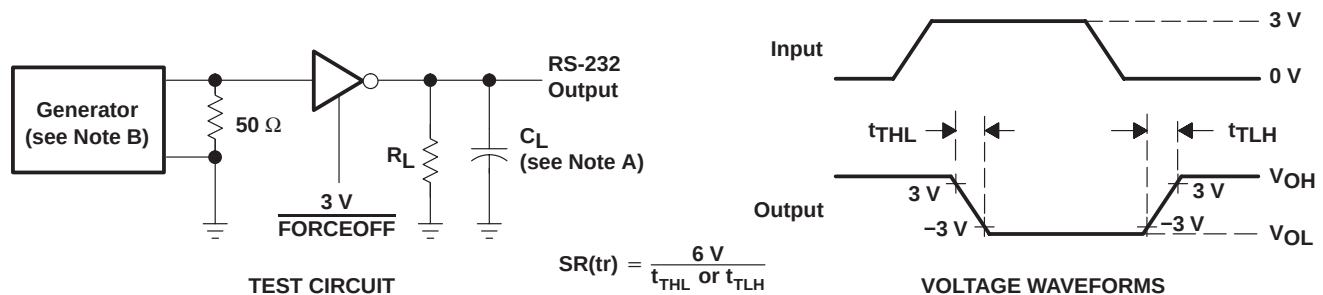
[†] All typical values are at V_{CC} = 3.3 V or V_{CC} = 5 V, and T_A = 25°C.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 5)

PARAMETER	MIN	TYP [†]	MAX	UNIT
t _{valid}		0.1		μs
t _{invalid}		50		μs
t _{en}		25		μs
t _{dis}	15	30	60	s

[†] All typical values are at V_{CC} = 3.3 V or V_{CC} = 5 V, and T_A = 25°C.

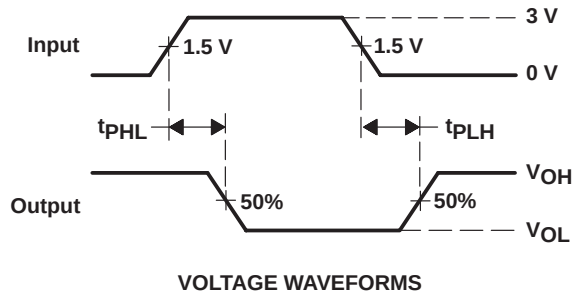
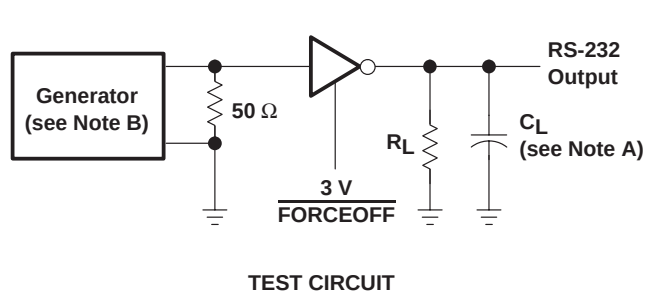
PARAMETER MEASUREMENT INFORMATION



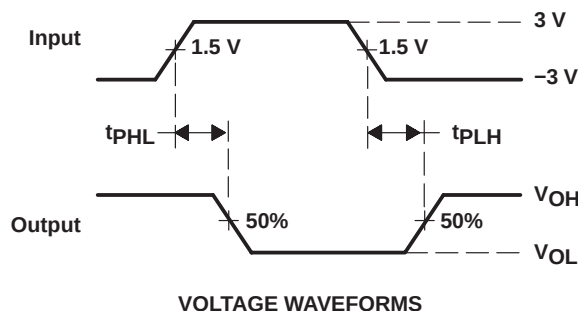
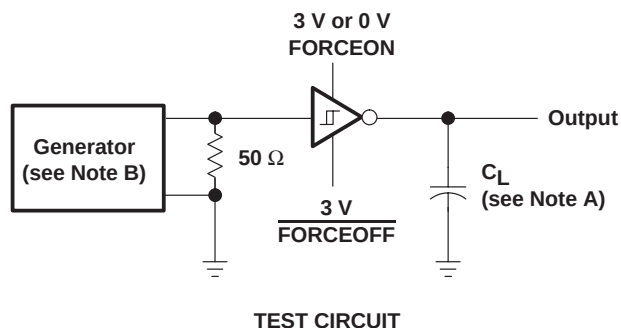
NOTES: A. C_L includes probe and jig capacitance.

B. The pulse generator has the following characteristics: PRR = 250 kbit/s, Z_O = 50 Ω, 50% duty cycle, t_r ≤ 10 ns, t_f ≤ 10 ns.

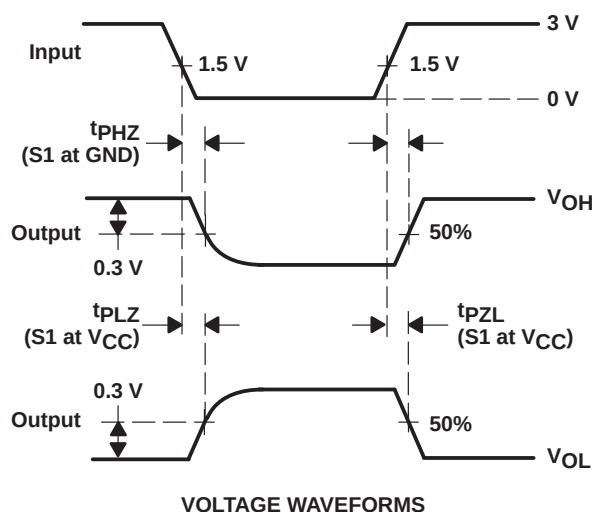
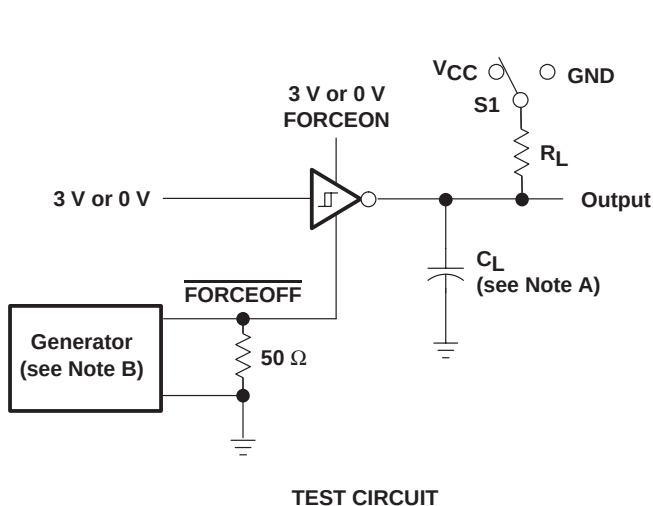
Figure 1. Driver Slew Rate

PARAMETER MEASUREMENT INFORMATION

 NOTES: A. C_L includes probe and jig capacitance.

 B. The pulse generator has the following characteristics: PRR = 250 kbit/s, $Z_O = 50\ \Omega$, 50% duty cycle, $t_r \leq 10\text{ ns}$, $t_f \leq 10\text{ ns}$.

Figure 2. Driver Pulse Skew

 NOTES: A. C_L includes probe and jig capacitance.

 B. The pulse generator has the following characteristics: $Z_O = 50\ \Omega$, 50% duty cycle, $t_r \leq 10\text{ ns}$, $t_f \leq 10\text{ ns}$.

Figure 3. Receiver Propagation Delay Times

 NOTES: A. C_L includes probe and jig capacitance.

 B. The pulse generator has the following characteristics: $Z_O = 50\ \Omega$, 50% duty cycle, $t_r \leq 10\text{ ns}$, $t_f \leq 10\text{ ns}$.

 C. t_{PLZ} and t_{PHZ} are the same as t_{dis} .

 D. t_{PZL} and t_{PZH} are the same as t_{en} .

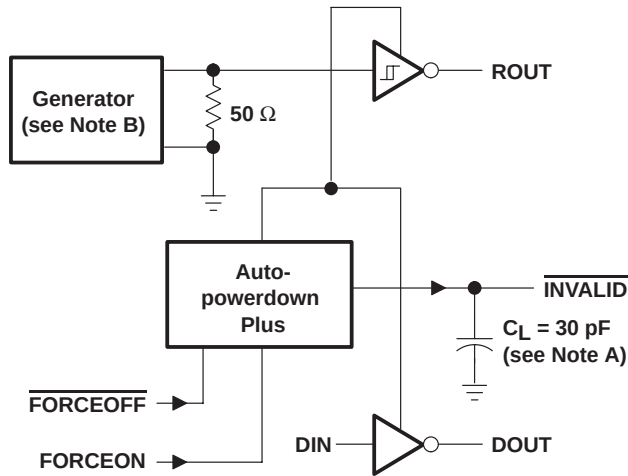
Figure 4. Receiver Enable and Disable Times

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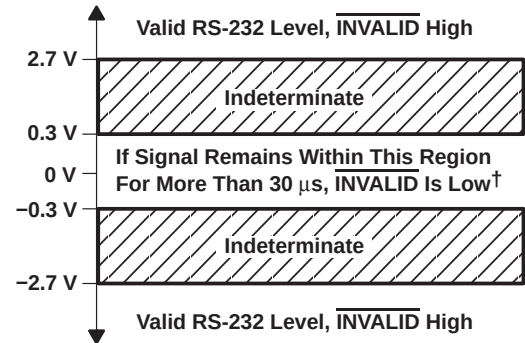
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PARAMETER MEASUREMENT INFORMATION



TEST CIRCUIT

- NOTES: A. C_L includes probe and jig capacitance.
B. The pulse generator has the following characteristics: PRR = 5 kbit/s, $Z_O = 50 \Omega$, 50% duty cycle, $t_r \leq 10$ ns, $t_f \leq 10$ ns.



† Auto-powerdown plus disables drivers and reduces supply current to 1 μ A.

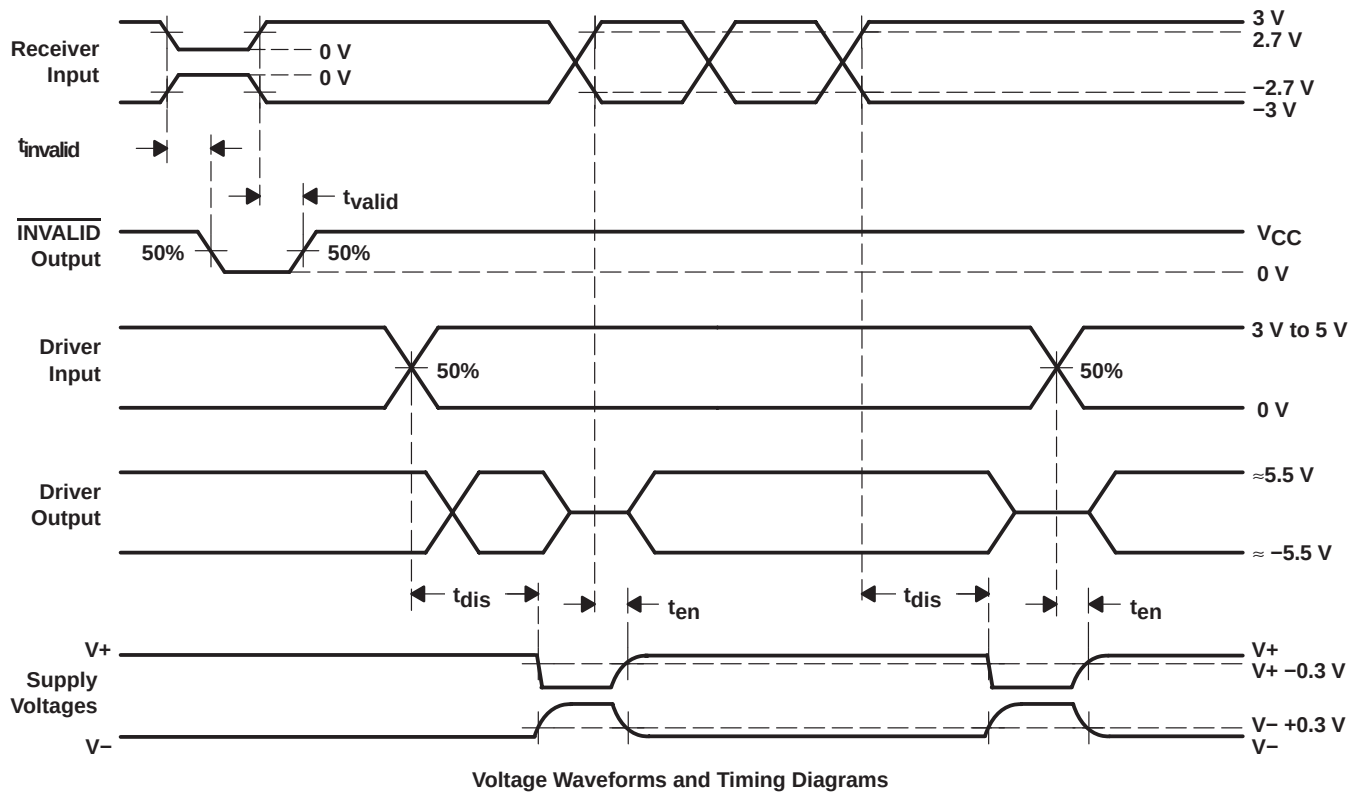


Figure 5. $\overline{\text{INVALID}}$ Propagation-Delay Times and Supply-Enabling Time

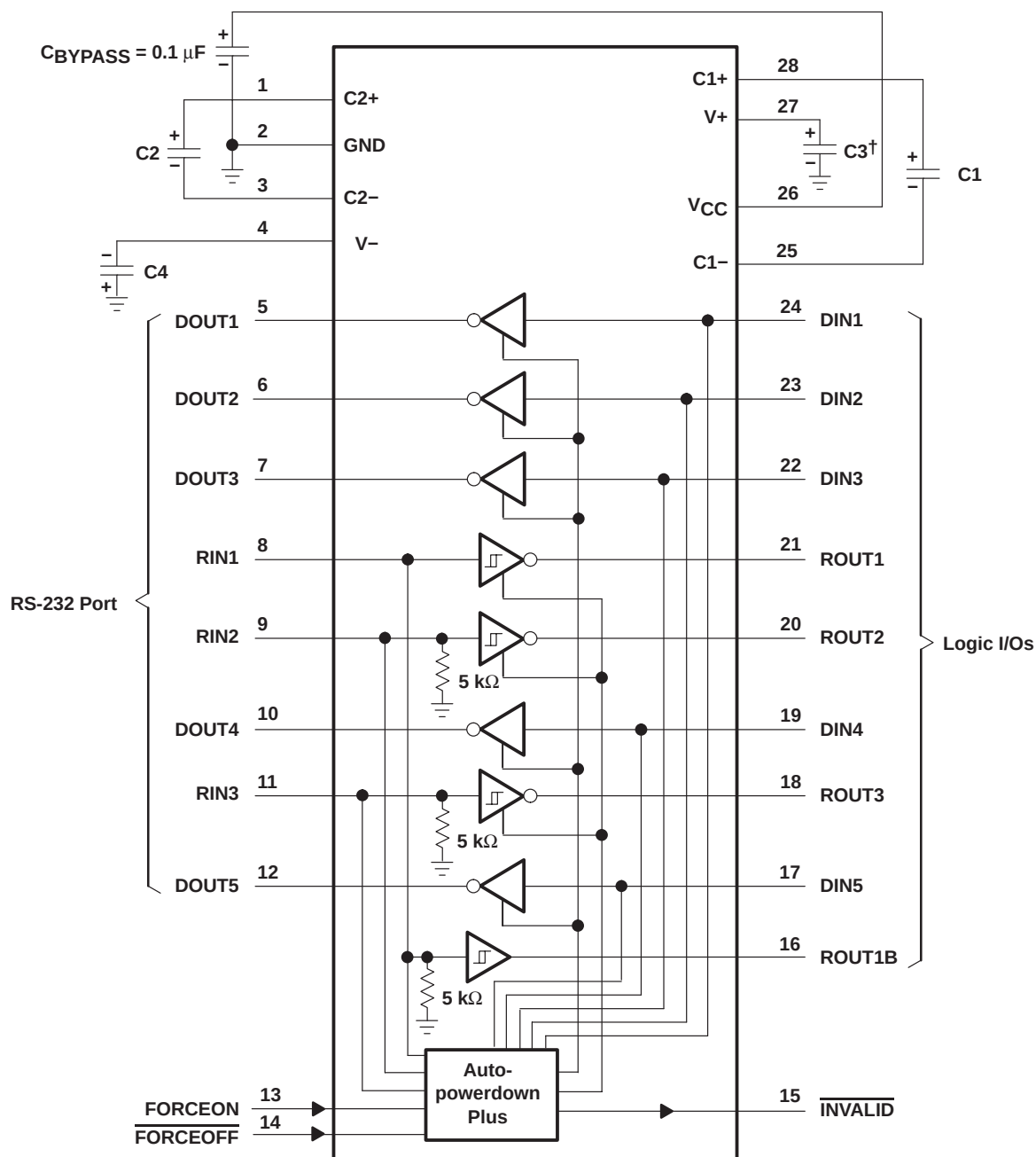
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APPLICATION INFORMATION



† C3 can be connected to V_{CC} or GND.

NOTES: A. Resistor values shown are nominal.

B. Nonpolarized ceramic capacitors are acceptable. If polarized tantalum or electrolytic capacitors are used, they should be connected as shown.

V_{CC} vs CAPACITOR VALUES

V_{CC}	C1	C2, C3, and C4
3.3 V $\pm$ 0.15 V	0.1 μ F	0.1 μ F
3.3 V $\pm$ 0.3 V	0.22 μ F	0.22 μ F
5 V $\pm$ 0.5 V	0.047 μ F	0.33 μ F
3 V to 5.5 V	0.22 μ F	1 μ F

Figure 6. Typical Operating Circuit and Capacitor Values

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
MAX3238CDBR	Active	Production	SSOP (DB) 28	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	MAX3238C
MAX3238CDBR.A	Active	Production	SSOP (DB) 28	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	MAX3238C
MAX3238CDBR.B	Active	Production	SSOP (DB) 28	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	MAX3238C
MAX3238CDBRE4	Active	Production	SSOP (DB) 28	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	MAX3238C
MAX3238CPWR	Active	Production	TSSOP (PW) 28	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	MA3238C
MAX3238CPWR.A	Active	Production	TSSOP (PW) 28	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	MA3238C
MAX3238CPWR.B	Active	Production	TSSOP (PW) 28	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	MA3238C
MAX3238IDBR	Active	Production	SSOP (DB) 28	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	MAX3238I
MAX3238IDBR.A	Active	Production	SSOP (DB) 28	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	MAX3238I
MAX3238IDBR.B	Active	Production	SSOP (DB) 28	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	MAX3238I
MAX3238IPWR	Active	Production	TSSOP (PW) 28	2000 LARGE T&R	Yes	NIPDAU NIPDAU	Level-1-260C-UNLIM	-40 to 85	MB3238I
MAX3238IPWR.A	Active	Production	TSSOP (PW) 28	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	MB3238I
MAX3238IPWR.B	Active	Production	TSSOP (PW) 28	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	MB3238I

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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OTHER QUALIFIED VERSIONS OF MAX3238 :

- Automotive : [MAX3238-Q1](#)

NOTE: Qualified Version Definitions:

- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

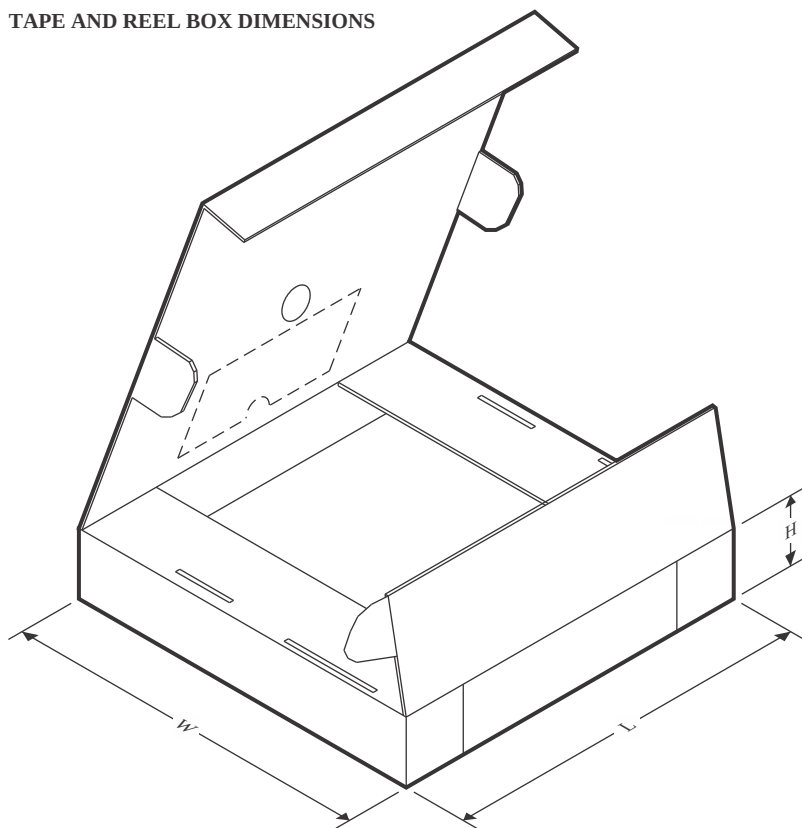
TAPE AND REEL INFORMATION



*All dimensions are nominal

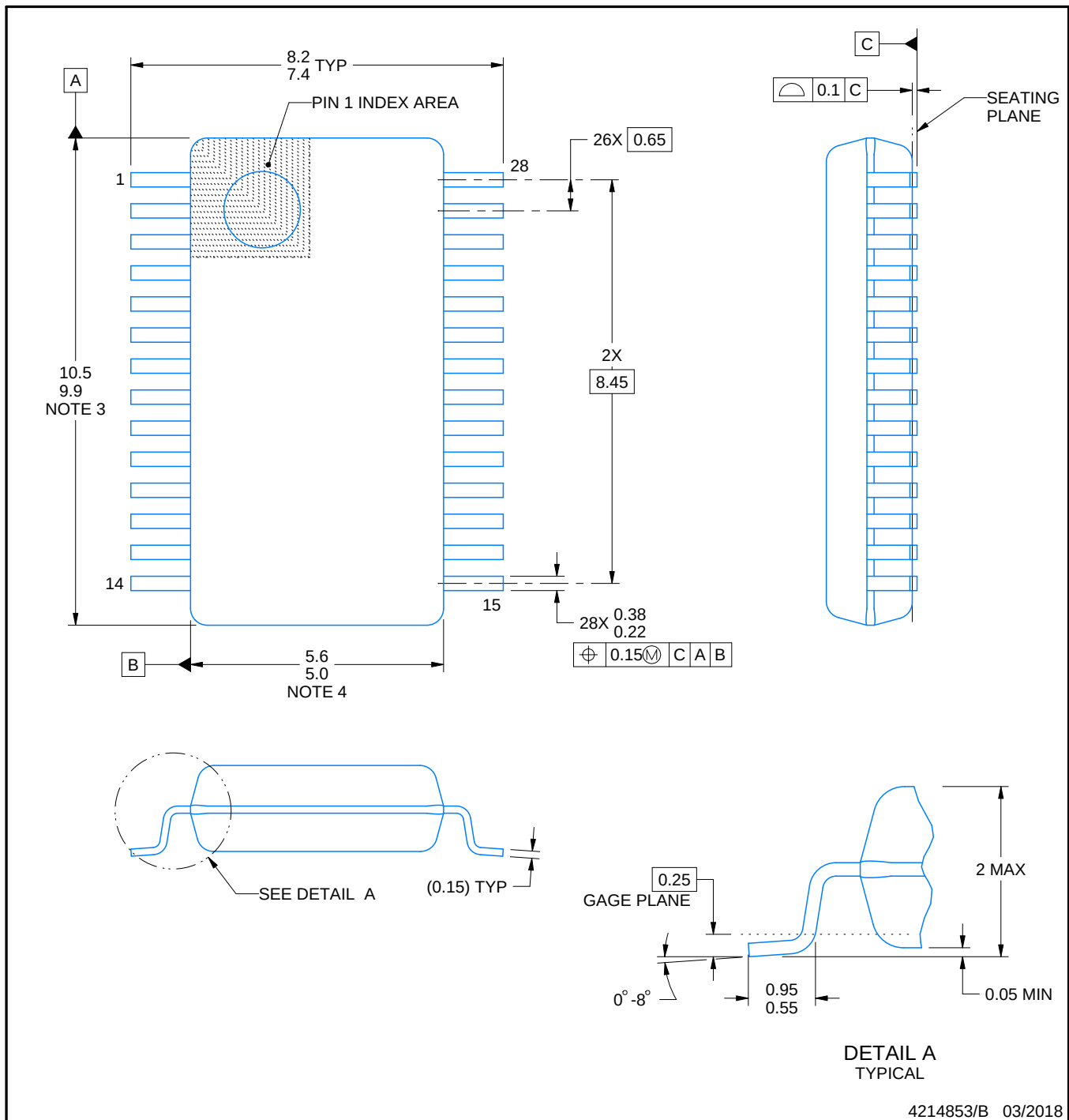
Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
MAX3238CDBR	SSOP	DB	28	2000	330.0	16.4	8.45	10.55	2.5	12.0	16.2	Q1
MAX3238CPWR	TSSOP	PW	28	2000	330.0	16.4	6.75	10.1	1.8	12.0	16.0	Q1
MAX3238IDBR	SSOP	DB	28	2000	330.0	16.4	8.45	10.55	2.5	12.0	16.2	Q1
MAX3238IPWR	TSSOP	PW	28	2000	330.0	16.4	6.75	10.1	1.8	12.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
MAX3238CDBR	SSOP	DB	28	2000	353.0	353.0	32.0
MAX3238CPWR	TSSOP	PW	28	2000	353.0	353.0	32.0
MAX3238IDBR	SSOP	DB	28	2000	353.0	353.0	32.0
MAX3238IPWR	TSSOP	PW	28	2000	353.0	353.0	32.0



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NOTES:

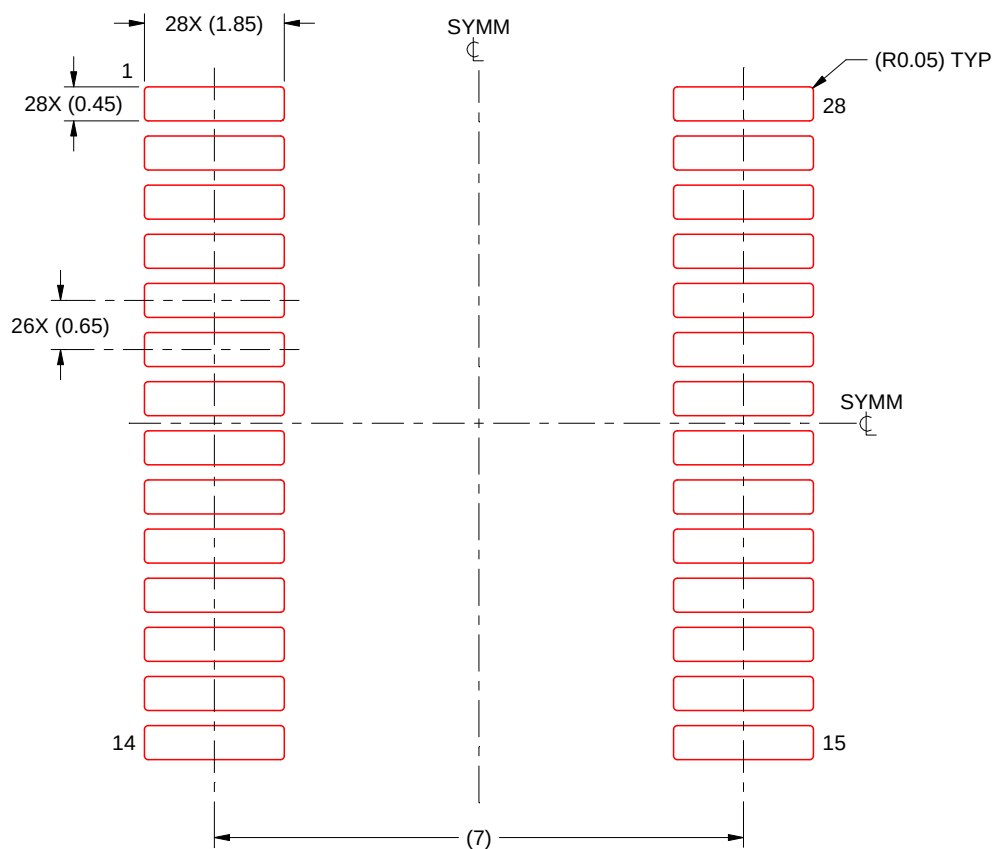
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-150.

EXAMPLE STENCIL DESIGN

DB0028A

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

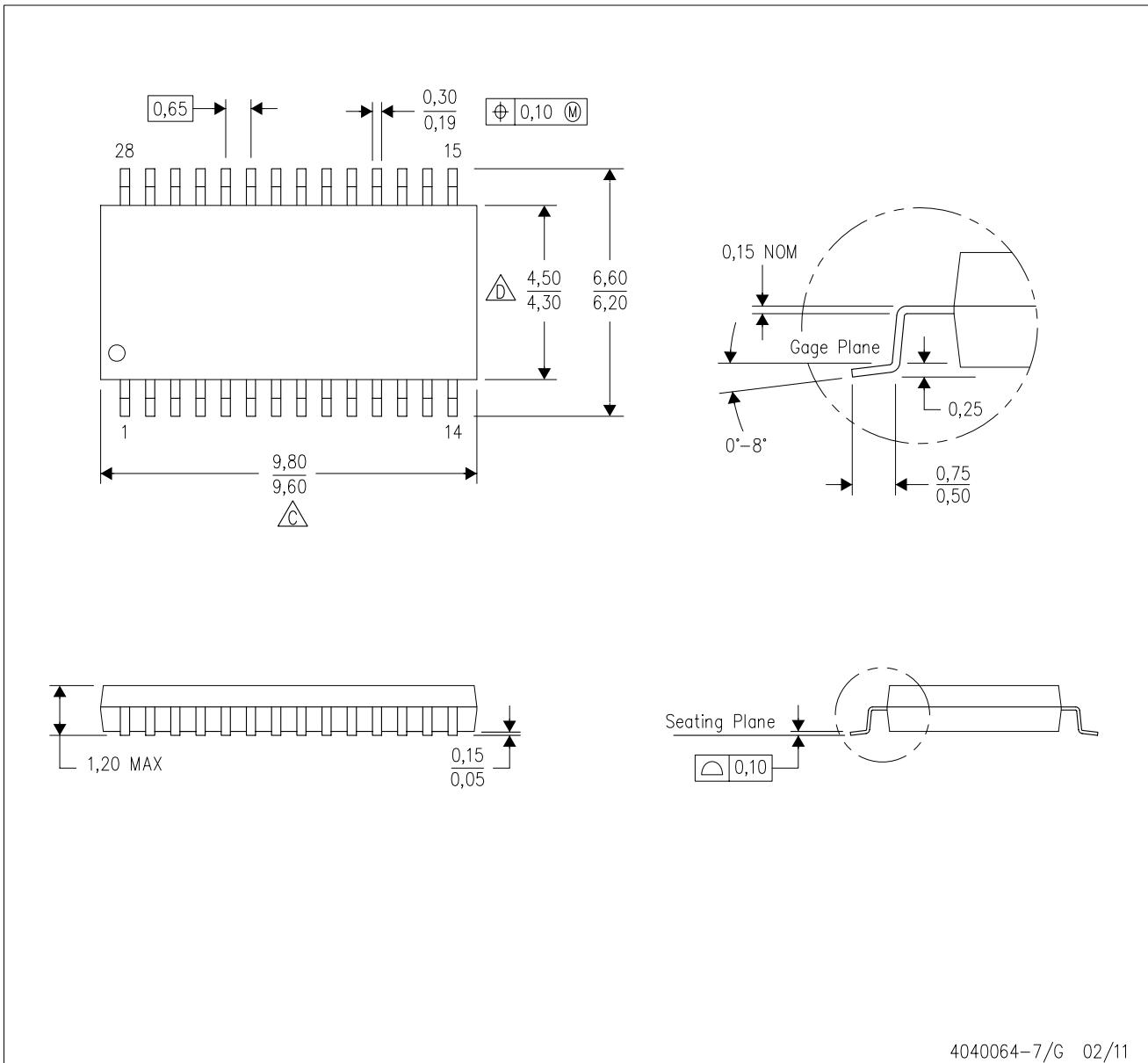
4214853/B 03/2018

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

PW (R-PDSO-G28)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
 - D. Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
 - E. Falls within JEDEC MO-153

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